L	Hits	Searci Text	DB	Time stamp
Number				0000/06/10
1	63	and capillary	USPAT; US-PGPUB	2003/06/13
2	45	and capillary) and @ad<=20010322	USPAT; US-PGPUB	2003/06/13
3	546		USPAT; US-PGPUB	2003/06/13
4	437	((bonding adj wire) and pad and capillary) and @ad<=20010322	USPAT; US-PGPUB	2003/06/13
5	392		USPAT; US-PGPUB	2003/06/13

review the tagged prior out after AMN 6/16/03

	ū	1 1 1	1 [1 Document ID]	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval Classif
П		Ø	US 20020100790 A1	20020801	12	Bonding tool with polymer coating	228/4.5		
7		Ø	US 20010002726 A1	20010607	26	Semiconductor device and method for making the same	257/678		
3		⊠	US 20010000157 A 1	20010405	19		438/617	257/693	
4		⊠	US 6564449 B1	20030520	11	Method of making wire connection in semiconductor device	29/830	29/40; 29/41; 29/46	
S		☒	US 6441495 B1	20020827	26	Semiconductor device of stacked chips	257/777	257/723; 257/784; 257/786	
9		⋈	US 6213384 B1	20010410	10	g method	228/180.5	228/1.1; 228/110.1; 228/4.5; 257/E21.51	
7		⊠	US 5994152 A	19991130	31	Fabricating interconnects and tips using sacrificial substrates	438/617	438/117; 438/15	

Inventor	S	၁	ц	2	3	41	2	Image Doc. Displayed	Τđ
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